



- NOTES: UNLESS OTHERWISE SPECIFIED.
1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
  2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
  3. MATERIAL SHALL BE COPPER CLAD FR-4, NEMA GRADE PER IPC-4101, COLOR NATURAL.
  4. CONSTRUCTION SHALL BE SYMMETRICAL MULTILAYER PER LAYER STACKUP DETAIL.
  5. COPPER WEIGHT ON INNER LAYERS SHALL BE 1.0 OZ./SQ. FT..
  6. COPPER WEIGHT ON OUTER LAYERS SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
  7. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.0007" COPPER.
  8. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE +/- .003".
  9. MINIMUM ANNULAR RING SHALL BE 0.001".
  10. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
  11. PCB THICKNESS SHALL BE 0.093" +/- 0.007". NOTE: SECTION -AA- SPECIAL BOARD CUTS ON TOP - BOTTOM EDGES.
  12. WARP/TWIST SHALL NOT EXCEED .010 INCH PER INCH.
  13. FINISH SHALL BE LPI, GREEN SMOBC, BOTH SIDES.
  14. SILKSCREEN BOTH SIDES WITH NONCONDUCTIVE WHITE EPOXY INK.
  15. REFERENCE ADDITIONAL FAB NOTES IN FILE RCUFBINP.302

LAYER STACKUP	FILE NAMES
TOP SILKSCREEN	RCUTSS.302
TOP SOLDER MASK	RCUTSM.302
COMPONENT SIDE	RCUCOMP.302
GND PLANE	RCUGND.302
INTERNAL 2 SIG 1	RCUNT1.302
INTERNAL 3 SIG 2	RCUNT2.302
VCC PLANE	RCUVCC.302
SOLDER SIDE	RCUSOLD.302
BOTTOM SOLDER MASK	RCUBSM.302
BOTTOM SILKSCREEN	RCUBSS.302
SCALE: NONE	

SIZE	QTY	SYM	PTLD	TOOL	TOLERANCE
20	1820	+	P	1	+0.002/-0.006
24	1070	X	P	2	+/-0.003
32	124	□	P	3	+/-0.003
35	814	◇	P	4	+/-0.003
40	195	⊠	P	5	+/-0.003
44	30	⊠	P	6	+/-0.003
48	25	A	P	7	+/-0.003
55	18	B	P	8	+/-0.003
63	7	C	P	9	+/-0.003
67	6	D	P	10	+/-0.003
80	2	E	P	11	+/-0.003
106	5	F	P	12	+/-0.003
130	14	G	P	13	+/-0.003
156	3	H	P	14	+/-0.003

SECONDARY SIDE  
PRIMARY SIDE  
AA

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Board Name: MUON PORT CARD	Part Number: .	Job No.: RCU.302	Date: 02-28-05